



 ■ Fully Supported ▲ = Limited Capability 	ANSYS Mechanical	ANSYS Mechanical	ANSYS Mechanical Pro	ANSYS DesignSpace	ANSYS Autodyn	ANSYS LS-DYNA	ANSYS AIM
□= Requires more than 1 product	Enterprise	Premium			•		
STRUCTURES							
Geometric Idealization							
Spring	•	•	A	A	•	•	
Mass	•	•	•	•	•	•	•
Damper	•	•			•	•	
Spar	•	•	•	•			
Beam	•	•	•	•	•	•	
Pipe/Elbow	•	•	•	•			
Shell - Thin	•	•	•	•	•	•	•
Layered Shell - Thin (Composite)	•	•			•	•	
Shell - Thick (Solid Shell)	•	•	•	•			
Layered Shell - Thick (Solid Shell)	•						
(Composite)							
2D Plane / Axisymmetric	•	•	•	•	•	•	
3D Solids	•	•	•	•	•	•	•
Layered 3D Solids (Composite)	•	•					
Infinite Domain	•	•	•		•	•	
2.5D	•	•					
Reinforced	•	•			•	•	
ROM	•						
Substructuring / Matrix	•						
Modeling Capabilities							
Contact - Linear	•	•	•	•	•	•	•
Contact - Nonlinear	•	•	•	A	•	•	•
Joints	•	•	•			•	•
Spot Welds	•	•	•		•	•	
Birth and Death	•						
Gaskets	•						
Rezoning and Adaptive Remeshing	•				•	•	
Materials							
Basic Linear Materials (Linear,		_					
Anisotropic, Temperature Dependent).	•	•	•	•	•	•	•
Basic Nonlinear Materials (Hyper,							
Plasticity, Rate Independent,	•	•			•	•	
Isotropic, Concrete).							
Advanced Nonlinear Materials (Rate							
dependent, Anisotropic, Damage Models,	•				•	•	A
Geomechanics Materials, Multiphysics).							
Field Dependent	•	•					
Reactive Materials	•				•		
Fracture Mechanics	•						

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▲ = Limited Capability □= Requires more than 1 product	Mechanical	Mechanical	Mechanical Pro	DesignSpace	Autodyn	LS-DYNA	
□= Requires more than 1 product	Enterprise	Premium					
Composite Materials							
Material Definitions	•	•			•	•	
Layers Definitions	•	A			•	•	
Solid Extrusion	•						
First-ply Failure	•	•					
Last-Ply failure	•						
Delamination	•				•	•	
Draping	•						
Structural Solver Capabilities							
Linear Static	•	•	•	•			•
Nonlinear Static	•	•	•	A			•
Pre-Stress effects, Linear perturbation	•	•	•	•	A	A	
Nonlinear Geometry	•	•	•		•	•	•
Buckling - Linear Eigenvalue	•	•	•	•			
Buckling - Nonlinear Post Buckling	•	•	•			•	•
Behavior							
Buckling - Nonlinear Post Buckling	•	•					
Behavior- Arc Length							
Steady State Analysis applied to a	•						
Transient Condition							
Advanced Wave Loading	•						
Topology Optimization							
Static Structural	•	•	•	•			•
Modal Analysis	•	•	•	•			•
Design Validation Transfer	•	•	•	•			•
Manufacturing Constraints	•	•	•	•			
Multi Analysis							
Submodeling	•	•	•	•			
Data Mapping	•	•	•				•
Trace Mapping	•	•					
Initial State	•	•			•	•	
Advanced Multi-Stage 2-D to	•	•					
3-D Analysis		-					
V°L							
Vibrations							
Modal	•	•	•	•			•
Modal - Pre-Stressed	•	•	•	•			
Modal - Damped/Unsymmetric	•	•					
Transient - Mode-Superposition	•	•					

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Harmonic - Mode-Superposition	•	•					
Harmonic - Full	•	•					
Spectrum	•	•					
Random Vibration	•	•					
Mistuning	•	•					
Rotordynamics	•	•					
Nonlinear Transient Dynamics							
Rigid Body Mechanisms	•	•					
Rigid Body Dynamics with CMS	-	-					
components for flexible bodies	•						
Full Transient	•				•	•	
CMS with Substructuring	•					-	
Explicit Dynamics							
FE (Lagrange) Solver	•				•	•	
Euler Solvers	<u> </u>				•		
Meshless Solvers					•		
Implicit-Explicit Deformations	•				•	•	
Implicit-Explicit Material States	•				•		
Fluid-Structure Interaction (FSI)					•		
Mass Scaling	•				•	•	
Natural Fragmentation	•				•		
Erosion Based on Multiple Criteria	•				•	•	
De-Zoning					•	•	
Part Activation and Deactivation					•		
(Multi Stage Analysis)					•		
Remapping in Space					•		
Remapping Solution Methods					•		
Remapping Solution Methods					•		
Durability							
Stress-Life (SN)	•	•	•				•
Strain-Life (EN)	•	•	•				•
Dang Van	□ 1	1	1				
Safety Factor	•	•	•				•
Adhesive Bond	□1	□1	□1				
Crack Growth Linear Fracture Mechanics	□1	□1	□1				
Seam Weld	□1	□1	□1				
Spot Weld	□1	□1	□1				
Thermo-mechanical Fatigue	□1	□ 1	□1				
Vibration Fatigue	□1	□ ¹	□1				
Virtual Strain Gauge Correlation	□1	□ 1	□1				
Python Scripting Customization	□1	□ 1	□ 1				

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Requires more than 1 product	Enterprise	Premium					
Wave Hydrodynamics							
Diffraction and Radiation	•						
Frequency & Time Domain Motions	•						
Analysis	_						
Moorings, Joints & Tethers	•						
Load Transfer to Structural Analysis	•						
Thermal							
Steady State Thermal	•	•	•	•			•
Transient Thermal	•	•	•				•
Conduction	•	•	•	•	•	•	•
Convection	•	•	•	•			•
Radiation to Space	•	•	•				•
Radiation - Surface to Surface	•	•	•				
Phase Change	•	•	•		•	•	
Thermal Analysis of Layered Shells and Solids	•	•					
Additional Physics							
1-D Thermal-flow	•	•	•				
1-D Coupled-field Circuits	•						
1-D Electromechanical transducer	•						
MEMS ROM	•						
Piezoelectric	•						
Piezoresistive	•						
Electroelastic	•						
Electromagnetic	•						A
Vibro-acoustics	•						
Migration	•						
Diffusion -Pore-fluid	•						
Diffusion-Thermal Structural-Electric	•						
Structural-Thermal-Electric-Magnetic	•						A
1-Way Fluid-Structure Interaction	□ ²	□ ²	□ ²				•
2-Way Fluid-Structure Interaction	□ ²						

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— Requires more than 1 product	Enterprise	Premium					
Optimization	1						
DesignXplorer Included	•	•	•	•	□ 3	□3	•
Parameters	•	•	•	•	•	•	•
Design Point Studies	•	•	•	•	•	•	•
Correlation Analysis	•	•	•	•			•
Design of Experiments	•	•	•	•			•
Sensitivity Analysis	•	•	•	•			•
Goal Driven Optimization	•	•	•	•			•
Six Sigma Analysis	•	•	•	•			•
Miscellaneous and Usability	1						
ANSYS SpaceClaim	•	□4	□ 4	□4	4		•
ANSYS Customization Suite (ACS)	•	□5	 5	□ 5	 5		•
Support ACT Extensions	•	•	•	•	•	•	•
Command snippet support	•	•	•				•
Batch run capability	•	•	•	•	•	•	•
External Code Interfaces	•	•		•	•		
HPC - Structures	+						
	2 (DMP + SMP) MAPDL						
Default Number of Cores	2 for Explicit 2 for RBD 2 for AQWA	2 (DMP + SMP)	2 (DMP + SMP)	2 (DMP + SMP)	1	1	2 (DMP + SMP) MAPDL
Parallel Solving on Local PC	•	•	•	•	•	•	•
Parallel Solving on Cluster	•	•	•		•	•	
GPU Support	□6 MAPDL - Yes Explicit - No RBD - No Agwa - No	□6	□ 6	□6			

1 = ANSYS nCode DesignLife Products

2 = ANSYS Fluent

3 = ANSYS DesignXplorer

4 = ANSYS SpaceClaim

5 = ANSYS Customization Suite (ACS)

6 = ANSYS HPC, ANSYS HPC Pack or ANSYS HPC Workgroup

DMP = Distributed-memory Parallel SMP = Shared-memory Parallel MAPDL = Mechanical APDL

Explicit = Autodyn

RBD = Rigid Body Dynamics

Aqwa = Aqwa



				ANSYS CF	D Enterprise				
■ = Fully Supported	ANSYS CF	D Premium							
▲ = Limited Capability	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS CFD	ANSYS CFD	ANSYS	ANSYS	ANSYS
□= Requires more than 1 product	FLUENT	CFX	POLYFLOW	Forte	FLO	Professional	FENSAP-ICE	AIM	Chemkin Pro
FLUIDS									
General Solver Capabilities									
Comprehensive Inlet and Outlet	•	•	•	•	•	•	•	•	
Conditions									
Steady-State Flow	•	•	•	•	•	•	•	•	•
Transient Flow	•	•	•	•	•		•	•	•
2-D and 3-D Flow	•	A	•	<u> </u>	A	A	•	<u> </u>	
Time Dependent Boundary Conditions	•	•	•	•	•		•	•	•
Customizable Materials Library	•	•	•	•	•	•	•	•	•
Fan Model	•	•			•		•		
Periodic domains	•	•	•	•	•	•	•	•	
Dynamic/moving-deforming mesh	•	•	•	•	•		•		
Overset Mesh	•								
Immersed-solid/MST method for		•	•		•				
moving parts									
Flow-driven solid motion (6DOF)	•	•			•				
Pressure-based coupled solver	•	•	•	•	•	•	•	•	•
Density-based coupled solver	•								•
Automatic on-the-fly mesh generation	•			•					•
with dynamic refinement									
Dynamic Solution-Adaptive	•	•		•	•	•	A		•
Mesh refinement									
Single Phase, non reacting flows									
Incompressible Flow	•	•	•		•	•		•	•
Compressible Flow	•	•		•	•		•	•	•
Porous Media	•	•	•		•			A	•
Non-Newtonian Viscosity	•	•	•		•			•	
Turbulence - Isotropic	•	•		•	•	•	•	•	
Turbulence - Anisotropic (RSM)	•	•			•				
Turbulence - Unsteady (LES/SAS/DES)	•	•							
Turbulence - Laminar/Turbulent	•	•					•	•	
Transition									
Flow Pathlines (Massless)	•	•	•		•	•	_	•	
Fan Model	•	•			•		•		
Acoustics (Source Export)	•	•			•				
Acoustics (Noise Prediction)	•								
Heat Transfer									
Heat Transfer Natural Convection		_			_				_
Conduction & Conjugate Heat Transfer	•	•			•			•	•
Internal Radiation - Participating Media	•	•	•		•	•	•	•	•
Internal Radiation - Transparent Media	•	•			•				
External Radiation	•	•						•	•
Solar Radiation & Load	•	•						•	
Julai Naulatiuli & LUdu									

				ANSYS CF	D Enterprise				
• = Fully Supported	ANSYS CF	D Premium							
▲ = Limited Capability	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS CFD	ANSYS CFD	ANSYS	ANSYS	ANSYS
□= Requires more than 1 product	FLUENT	CFX	POLYFLOW	Forte	FLO	Professional	FENSAP-ICE	AIM	Chemkin Pro
Particles Flows (Multiphase)									
Coupled Discrete Phase Modeling	•	•		•			•	•	•
Inert Particle Tracking (With Mass)	•	•						•	
Liquid Droplet (Incl. Evaporation)	•	•		•			•	•	
Combusting Particles	•	•		•					•
Multicomponent Droplets	•	•		•			•		
Discrete Element Model (DEM)	•								
Break-Up And Coalescence	•	•		•			•		
For a Confirm Floor (Model to be an)									
Free Surface Flows (Multiphase) Implicit And Explicit VOF		_	•		_				
Coupled Level Set/VOF	•	•	•		•				
Open Channel Flow And Wave	•	•							
Surface Tension	•	•		•	•				
Phase Change	•	•		•	•				
Cavitation	•	•		•	•				
Dispersed Multiphase Flows									
(Multiphase)									
Mixture Fraction	•	•							
Eulerian Model	•	•		•			•		
Boiling Model	•	•		•					
Surface Tension	•	•		•					
Phase Change	•	•		•			•		•
Drag And Lift	•	•		•			•		
Wall Lubrication	•	•		•					
Heat And Mass Transfer	•	•		•			•		•
Population Balance	•	•		•					•
Reactions Between Phases	•	•		•					•
Reacting Flows									
Species Transport	•	•	•	•	•				•
Non-Premixed Combustion	•	•		•					•
Premixed Combustion	•	•		•					•
Partially Premixed Combustion	•	•		•					•
Composition PDF Transport	•	•							
Finite Rate Chemistry	•	•	•	•					•
Pollutants And Soot Modeling	•	•		•				· ·	•
Sparse chemistry solver with dynamic									
cell clustering and dynamic adaptive	•			•					•
chemistry									
Ability to use Model Fuel Library	•			•					•
mechanisms		<u> </u>							

ANSYS

				ANSYS CFD	Enterprise				
■ = Fully Supported	ANSYS CF	D Premium							
▲ = Limited Capability □= Requires more than 1 product	ANSYS FLUENT	ANSYS CFX	ANSYS POLYFLOW	ANSYS Forte	ANSYS CFD FLO	ANSYS CFD Professional	ANSYS FENSAP-ICE	ANSYS AIM	ANSYS Chemkin Pro
Flame-speed from Fuel-component				•					
Library									
DPIK Spark-ignition Model				•					
Flame-propagation using level-set				•					
method (G-equation)									
Internal Combustion Engine	•	•		•					•
Specific Solution									
0-D/1-D/2-D reactor models and									•
reactor networks									
Plasma reactions									•
Comprehensive surface-kinetics	•								•
Chemical and phase equilibrium	•								•
Flamelet table generation	•								•
Flamespeed and ignition table									•
generation									
Reaction sensitivity, uncertainty									•
and path analysis									
Surrogate blend optimizer									•
Mechanism Reduction									•
Turbomachinery									
MRF/Frozen-Rotor	•	•							
Sliding-Mesh/Stage	•	•							
Transient Blade Row		•							
Pitch Change		•							
Fourier Transformation		•							
Harmonic Analysis		•							
Blade Flutter Analysis		•							
Forced Response Analysis		•							

				ANSYS CF	D Enterprise				
● = Fully Supported	ANSYS CF	D Premium							
▲ = Limited Capability □= Requires more than 1 product	ANSYS FLUENT	ANSYS CFX	ANSYS POLYFLOW	ANSYS Forte	ANSYS CFD FLO	ANSYS CFD Professional	ANSYS FENSAP-ICE	ANSYS AIM	ANSYS Chemkin Pro
In-Flight Icing									
Simulates Droplet Sizes							•		
Simulates Ice Growth and Performs Visibility Studies							•		
Models Heat Transfer Anti- and							•		
De-icing Heat Loads									
Rotating frame of reference for the analysis of turbomachines, rotors and propellers							•		
Model ice accretion at engine face									
(Fan and IGV) and within any number							A		
of successive compressor stages									
Aerodynamic degradation (CFD) meets									
the requirements of Appendix C, Appendix D (Ice Crystals) and							•		
Appendix O (SLD)									
Shape Optimization									
Adjoint Solver for Sensitivity Analysis	•								
Mesh Morphing	A								
High Rheology Material									
Viscoelasticity			•						
Specialty Extrusion Models			•						
Specialty Blow Molding Models			•						
Specialty Fiber Spinning Models	•								
HPC – Fluids									
Parallel Solving On Local PC Option	•	•	•	•	•	•	•	•	
Parallel Solving Over Network Option	•	•	•	•	•	•	•		
CPU Support	•	•	•	•	•	•	•	•	
GPU Support	•		•						

				ANSYS CF	D Enterprise				
■ = Fully Supported	ANSYS CF	D Premium							1
▲ = Limited Capability□= Requires more than 1 product	ANSYS FLUENT	ANSYS CFX	ANSYS POLYFLOW	ANSYS Forte	ANSYS CFD FLO	ANSYS CFD Professional	ANSYS FENSAP-ICE	ANSYS AIM	ANSYS Chemkin Pro
MULTIPHYSICS									
Platform Technologies									
Advanced, Automated Data Exchange	•	•	•		•	•	•	•	
Accurate Data Interpolation Between	•	•			•	•	•	•	
Dissimilar Meshes									
Drag-n-Drop Multiphysics	•	•	•		•	•			
Direct Coupling Between Physics	•	•			•	•		•	
Collaborative Workflows	•	•			•	•		•	
Fully Managed Co-Simulation	•								
Flexible Solver Coupling Options	•	•			•	•	•		
Fluid-Structure Interaction									
Force Induced Motion/Deformation	•	•	•		•	•		•	
Fluid Thermal Deformation	•	•			•	•		•	
Electro-Thermal Interaction									
Convection Cooled Electronics	•								
Conduction Cooled Electronics	•								
High Frequency Thermal Management	•								
Electromechanical Thermal	•								
Management									
Other Coupled Interactions									
Aero-Acoustics	•								
Acoustics-Structural	•	•							
Fluid Magnetohydrodynamics	A								



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= Requires more than 1 product	Maxwell	HFSS	SIwave	Q3D Extractor	Icepak
ELECTRONICS					
Low Frequency Electromagnetics					
Electrostatics	•				
AC Conduction	•				
DC Conduction	•				
Magnetostatics	•				
Adaptive Field Mesh	•	•	•	•	
AC Harmonic Magnetic	•				
Electric Transient	•				
HPC Frequency Sweeps	•				
HPC Enabled Matrix Multiprocessing	•				
HPC Time Distribution Solver	•				
Magnetic Transient					
Translational Motion	•				
Fully Automatic Symmetrical	•				
Mesh Generation	•				
Layered Mesh Generation	•				
Rotational Motion	•				
Non-Cylindrical Motion	•				
Advanced Embedded Circuit Coupling	•				
Circuit Coupling with Adaptive	•				
Time Stepping	-				
Direct and Iterative Matrix Solvers	•				
Advanced Magnetic Modeling					
Vector Hysteresis Modeling	•				
Hysteresis Modeling for Anisotropic Material	•				
Nonlinear Reduced Order Models	•				
Frequency Dependent Reduced	•				
Order Models	•				
Equivalent Model Extraction	•				
(Linear-Motion, Rotational-Motion, No-Motion)	•				
Nonlinear Anisotropic Materials	•				
Functional Magnetization Direction	•				
Magnetization/De-magnetization	•				
Modeling					
Temperature De-magnetization	•				
Modeling	_				
Core Loss computation	•				
Lamination Modeling	•				
Magnetostriction and Magnetoelastic Modeling	•				

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□= Requires more than 1 product	Maxwell	HFSS	SIwave	Q3D Extractor	Icepak
Integrated Motor Synthesis and					
Design Kit	•				
Integrated Planar Magnetics	_				
Synthesis and Design Kit	•				
Integrated System and Circuit					
Simulation (Simplorer Entry)	•				
High Frequency Electromagnetics					
Multi-frequency broadband adaptive		_			
meshing		•			
Frequency and Time Domain Analysis					
Eigenmode Analysis		•			
Hybrid Finite Element/Integral					
Equation Analysis		•			
Hybrid Finite Element/Shooting and					
Bouncing Ray Analysis					
Modal Wave Port Excitation		•			
Lumped, Voltage and Current		•			
Excitations					
Floquet Excitations		•			
Incident Wave Excitation		•			
Magnetic Ferrite Bias Excitation		•			
Terminal Solutions		•			
Perfect Electric and Magnetic Boundary		•			
Finite Conductivity Boundaries		•			
Lumped RLC Boundary		•			
Symmetry Boundary		•			
Periodic Boundary		•			
Frequency dependant materials		•			
Higher and Mixed order Elements		•			
Curvilinear Elements		•			
Fully automated adaptive		•			
mesh refinement					
S,Y,Z Matrix Results		•			
E, H, J, P Field Results		•			
Direct and Iterative Matrix Solvers		•			
HPC Accelerated Frequency Sweeps		•			
HPC Enabled Matrix Multiprocessing		•			
HPC Distributed Hybrid Solving		•			
Antenna Parameter Calculation		•			
Infinite and Finite Antenna Array					
Calculations					
Radar Cross Section calculation		•			
FSS, EBG and Metamaterial Calculation		•			

DE= Requires more than 1 product Specific Absorption Rate Calculation Emil/EMC Calculation System Level EMI and RFI analysis Linear Circuit Analysis with EM Dynamic link Integrated Antenna Synthesis and Design Kit Integrated Links to Delcross Savant Shooting and Bouncing Ray+ (SBR+) Solver Integrated Links to Delcross EMIT RFI/EMI System Solver Integrated Links to Delcross EMIT RFI/EMI System Solver Integrated Links to Delcross EMIT RFI/EMI System Solver Integrated Links to Delcross EMIT RFI/EMI System Solver Integrated Initiation (Alitium, Cadence, Mentor, Pulsonix, & Zuken) MCAD (Sad) Generation from ECAD ELead Frame Editor DC Voltage, Current and Power Analysis for PKG/PCB DC Joule Heating with ANSYS Lepak PAssive Excitation Plane Resonance Analysis for PKG/PCB Analysis or PKG/PCB Audity in Analysis or PKG/PCB Audity in Analysis or PKG/PCB Analysis or Doubling Analysis AC SYZ Analysis - PI, SI, & EMI Dynamically Linked Electromagnetic Field Solvers Linear Field EMI Analysis Far-Field EMI Analysis	• = Fully Supported	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS
EMI/EMC Calculation System Level EMI and RFI analysis Linear Circuit Analysis with EM Dynamic link Integrated Antenna Synthesis and Design Kit Integrated Links to Delcross Savant Shooting and Bouncing Ray+ (SBR+) Solver Integrated Link to Delcross EMIT RFI/EMI System Solver Integrated Parametric 3D Component Libraries Power and Signal Integrity Board Simulation Capabilities Electronics Desktop 3D Layout GUI ECAD Translation (Altium, Cadence, Mentor, Pulsonix, & Zuken) MCAD (sas) Generation from ECAD Lead Frame Editor DC Voltage, Current and Power Analysis for PKC/PCB DC Joule Heating with ANSYS Icepak Passive Excitation Plane Resonance Analysis Automated Decoupling Analysis AC SYZ Analysis - P, SI, & EMI Dynamically Linked Electromagnetic Field Solvers Chip, Package, PCB Analysis (CPM) PC SYZ Packed C(Zo) PKC/PCB Scan PKILPC BC Scan PKILPC PKC FC Scsat BC Scanning	▲ = Limited Capability □= Requires more than 1 product	Maxwell	HFSS	SIwave	Q3D Extractor	Icepak
EMI/EMC Calculation System Level EMI and RFI analysis Linear Circuit Analysis with EM Dynamic link Integrated Antenna Synthesis and Design Kit Integrated Links to Delcross Savant Shooting and Bouncing Ray+ (SBR+) Solver Integrated Link to Delcross EMIT RFI/EMI System Solver Integrated Parametric 3D Component Libraries Power and Signal Integrity Board Simulation Capabilities Electronics Desktop 3D Layout GUI ECAD Translation (Altium, Cadence, Mentor, Pulsonix, & Zuken) MCAD (sas) Generation from ECAD Lead Frame Editor DC Voltage, Current and Power Analysis for PKC/PCB DC Joule Heating with ANSYS Icepak Passive Excitation Plane Resonance Analysis Automated Decoupling Analysis AC SYZ Analysis - P, SI, & EMI Dynamically Linked Electromagnetic Field Solvers Chip, Package, PCB Analysis (CPM) PC SYZ Packed C(Zo) PKC/PCB Scan PKILPC BC Scan PKILPC PKC FC Scsat BC Scanning	Specific Absorption Rate Calculation		•			
System Level EMI and RFI analysis Linear Circuit Analysis with EM Dynamic link Integrated Antenna Synthesis and Design Kit Integrated Links to Delcross Savant Shooting and Bouncing Ray+ (SBR+) Solver Integrated Link to Delcross EMIT RFI/EMI System Solver Integrated Parametric 3D Component Libraries Power and Signal Integrity Board Simulation Capabilities Electronics Desktop 3D Layout GUI ECAD Translation (Altium, Cadence, Mentor, Pulsonii, & Zuken) MCAD (.sat) Generation from ECAD Lead Frame Editor DC Voltage, Current and Power Analysis for PKG/PCB DC Joule Heating with ANSYS Icepak Passive Excitation Plane Resonance Analysis Oriven Excitation Plane Resonance Analysis Capacitor Loop Inductance Analysis AC SYZ Analysis - P, SI, & EMI Dynamically Linked Electromagnetic Field Solvers Chip, Package, PCB Analysis (CPM) HPC SYZ Speed Up Near-Field EMI Analysis Far-Field EMI Analysis Far-Field EMI Analysis Far-Field EMI Analysis Far-Field EMI Analysis Fall UI PCB/PKG Cross-talk Scanning • UI UP CB/PKG Cross-talk Scanning						
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Full PCB/PKG Cross-talk Scanning						
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■ = Fully Supported	ANSYS	ANEVE	ANCVC	ANSYS	ANSYS
▲ = Limited Capability	1	ANSYS	ANSYS	7	7
□= Requires more than 1 product	Maxwell	HFSS	SIwave	Q3D Extractor	Icepak
Transient IBIS Circuit Analysis			•		
SerDes IBIS-AMI Circuit Analysis					•
Macro-Modeling (Network Data Explorer)		•	•		
Steady State AC (LNA) Analysis		•	•		
Virtual Compliance - DDRx, GDDRx,		-			
& LPDDRx			•		
Synopsys HSPICE Integration			•		
Cadence PSPICE Support			•		
Electromagnetically Circuit Driven		•	•		
Field Solvers					
RLCG Parasitic Extraction					
DCRL, ACRL & CG Solver			•	•	
IC Packaging RLCG IBIS Extraction			•	•	
for Signals & Power				, and the second	
Touchpanel RLCG Unit Cell Extraction			•	•	
Adaptive Meshing for Accurate				•	
Extraction					
Bus Bar RLCG Extraction				•	
Power Inverter & Converter				•	
Component Extraction					
Specialized Thin Plane Solver for				•	
Touchpanel Extraction					
HPC Acceleration for DCRL, ACRL,				•	
and CG 3D Component Library					
3D Component Library		•		•	
Reduced RLCG Matrix Operations				•	
SPICE equivalent Modeling Export				•	
DCRL & ACRL Joule Heating Analysis				•	
with Icepak				•	
Macro-modeling (Network Data Explorer)				•	
2D Transmission Line Modeling Toolkit				•	
2D Cable Modeling Toolkit				•	
בט כמטופ ויוטעפנוווא וטטנאונ				•	

 ■ = Fully Supported ▲ = Limited Capability □ = Requires more than 1 product 	ANSYS Maxwell	ANSYS HFSS	ANSYS SIwave	ANSYS Q3D Extractor	ANSYS Icepak
Electronics Cooling					
Multi-mode Heat Transfer					•
Steady-state and Transient					•
CFD Analysis					•
Turbulent Heat Transfer					•
Multiple-fluid Analysis					•
Species Transport					•
Solar Loading					•
Reduced Order Flow and Thermal					•
Network Modeling					•
Joule Heating Analysis	•	•	•	•	•
Thermo-electric Cooler Modeling				•	•
Thermostat Modeling					•
Package Characterization					•
Data Center Modeling					•
Data center Flodering					
Multiphysics					
Platform Technologies					
Advanced, Automated Data Exchange	•	•			
Accurate Data Interpolation Between	•	•			
Dissimilar Meshes	•	•			
Drag-n-Drop Multiphysics	•	•			
Direct Coupling Between Physics	•	•			
Collaborative Workflows	•	•			
Fully Managed Co-Simulation	•	•			
Flexible Solver Coupling Options	•	•			
1 5 1					
Electro-Thermal Interaction					
Convection Cooled Electronics		•			•
Conduction Cooled Electronics		•			•
High Frequency Thermal Management		•			
Electromechanical Thermal Management	•				



■ = Fully Supported				
▲ = Limited Capability	ANSYS	ANSYS SCADE	ANSYS SCADE	ANSYS SCADE
= Requires more than 1 product	Simplorer	Architect	Suite	Display
SYSTEMS & EMBEDDED SOFTWARE				
Virtual Systems Prototyping				
			Δ.	
Integrated Graphical Modeling Environment	•		A	
Standard Modeling Languages and			A	
Exchange Formats	•		•	
Extensive Model Libraries	•		A	
Reduced Order Modeling (ROM)			<u> </u>	
Power Electronic Device And				
Module Characterization	•			
Model Import Interfaces	•		<u> </u>	
Rapid Prototyping	•		<u> </u>	
Modelica Library Integration	•		<u> </u>	
Modelica Library Integration				
Model-based Systems Engineering				
Model-Based System Design		•		
Functional Decomposition		•		
Architecture Decomposition		•		
Allocation Of Functions To				
Components		•		
Model Checks		•		
System Model Diff/Merge		•		
System / Software Bi-Directional Sync		•		
Model Sharing And IP Protection		•		
Model-Based Interface Control				
Document Production		•		
Configurable For Industry Standards				
(IMA, AUTOSAR, Etc.)		•		
Product configuration for automotive				
developers		•		
Embedded Control Software				
Development				
Data Flow And State Machine Design			•	
And Simulation Capabilities				
Extensive Set Of Libraries Delivered			•	
As Design Examples				
Simulation Capabilities			•	
Record And Playback Scenarios			•	
Integration In To Configuration			•	
Management Environment				
Plant Model Co-Simulation Including			•	
FMI Coverage Applysis For Dequirements				
Coverage Analysis For Requirements-			•	
Based Tests				

 ■ = Fully Supported ▲ = Limited Capability □ = Requires more than 1 product 	ANSYS Simplorer	ANSYS SCADE Architect	ANSYS SCADE Suite	ANSYS SCADE Display
Formal Verification			•	
Timing And Stack Optimization			•	
Worst Case Execution Time Estimates On Target			•	
Verification Of Stack Space Requirements	3		•	
Certified Code Generation For DO-178C, EN 50128, ISO 26262, IEC 61508			•	
Certification Kits For DO-178C, EN50128, ISO 26262, IEC 61508			•	
Man-Machine Interface Software				
Model-Based Prototyping And Specification Of MMIs				•
Support Of OpenGl, OpenGl SC and OpenGL ES				•
Integration In To Configuration Management Environment				•
Font Management				•
Optimization Of Graphical Specifications				•
Plant Model Co-Simulation Including FMI				•
Automatic Generation Of iOS and Android Projects				•
Certified Code Generation For DO-178C, EN 50128, ISO 26262, IEC 61508				•
Certification Kits For DO-178C, EN50128, ISO 26262, IEC 61508				•
Testing capabilities				•



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GEOMETRY				
Open data from all major CAD systems	•	•	•	•
Edit designs and prepare them for simulation	•	•	•	•
Simplify geometry by removing features (eg rounds and holes)	•	•	•	•
Clean up and repair dirty geometry to create watertight solids	•	•	•	•
Create parameters on imported geometry to enable optimization of designs through analysis	•	•	•	•
Extract mid-surfaces/shells and beams solid models for efficient meshing and solving	•	•	•	•
Extract volumes/create inner fluid domains and outer air enclosures for CFD	•	•	•	•
Create shared topology among bodies to generate conformal meshes	•	•	•	•
Slicing of models into hex meshable bodies	•	•	•	•
Create weld bodies to simulate welds between shells	•	•	•	•
Define regions of symmetry for symmetric analysis			•	
Define named selections to aid in scoping of loads and boundary conditions	•	•	•	•
Scripting	•	•	•	•
2D drawing and editing tools	•	•	•	•
2D dimensioning and constraints			•	A
Supply 3D markups and compare models to document changes to design teams	•	•		•
Repair and edit faceted files for further FEA topological optimization and CFD analysis	•	•		•
Early Concept Design (bid modeling/ brainstorming/concepting)				
Create new concepts quickly and easily with four tools: Pull, Move, Fill, Combine	•	•		•

 ■ = Fully Supported ▲ = Limited Capability □ = Requires more than 1 product 	ANSYS AIM	ANSYS Enterprise	ANSYS Design Modeler	ANSYS SpaceClaim Direct Modeler
Use Cut, Copy, Paste, etc for fast ideation from existing designs	•	•		•
Enable 2d and 3D communication and collaboration with 3D Markup, Dimensions, and Drawing tools	•	•		•
Create BOM to evaluate weights and lengths for cost calculations	•	•		•
Make real-time edits with customers in LiveReview				•
Use automated tools to repair dirty geometry	•	•	•	•
Use top down or bottom up modeling	•	•	•	•
Create 2D drawings	•	•		•
Import and edit large assemblies	•	•		•



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Competence Center



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